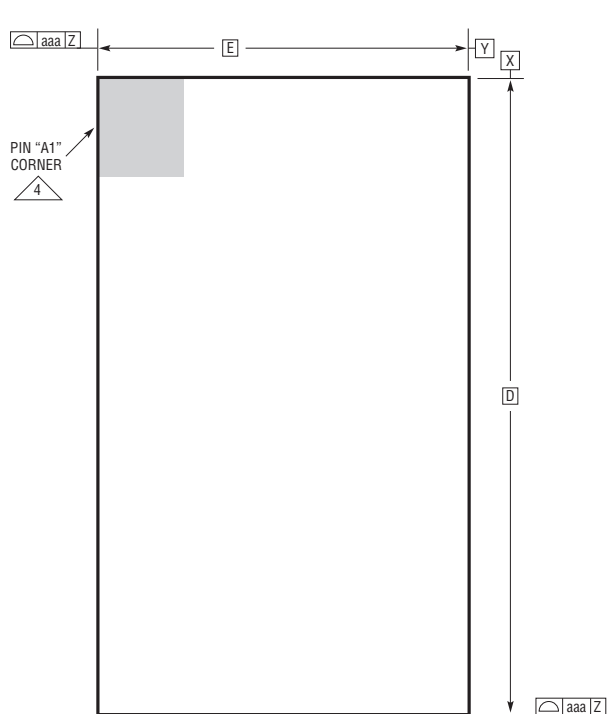
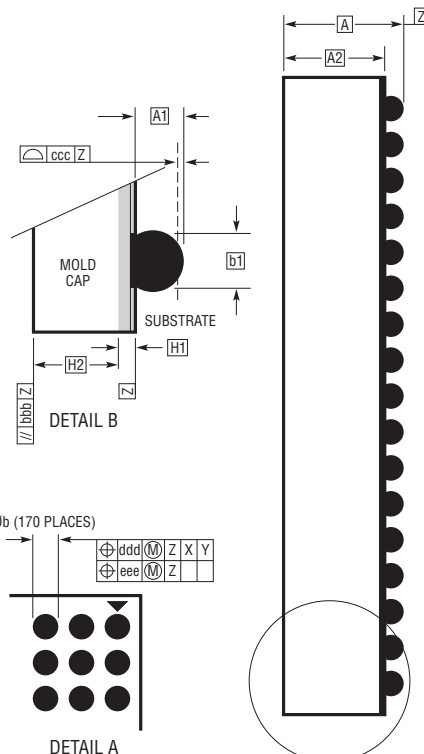


BGA Package
170-Lead (15.00mm × 9.00mm × 1.54mm)
 (Reference LTC DWG# 05-08-1890 Rev B)

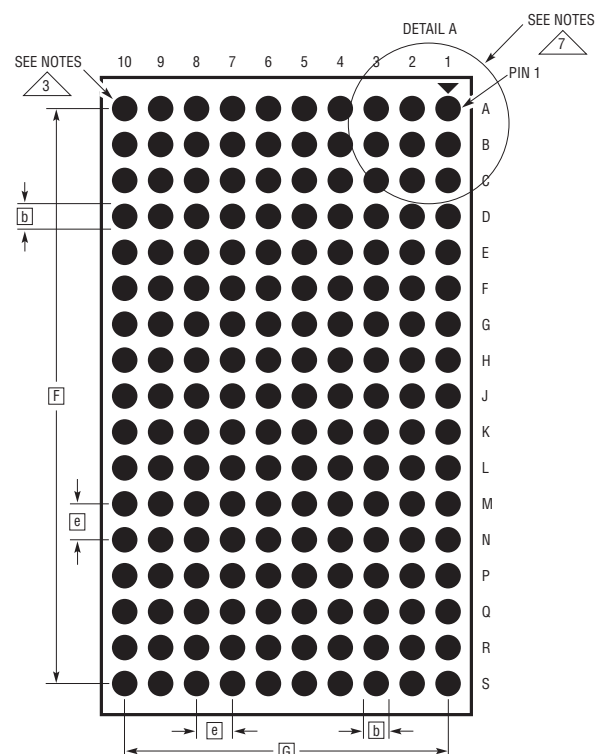


PACKAGE TOP VIEW

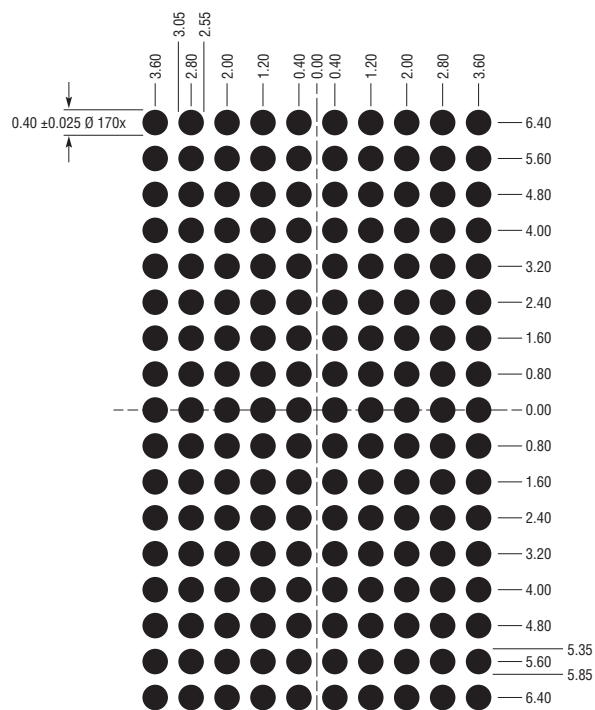


DETAIL A

DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



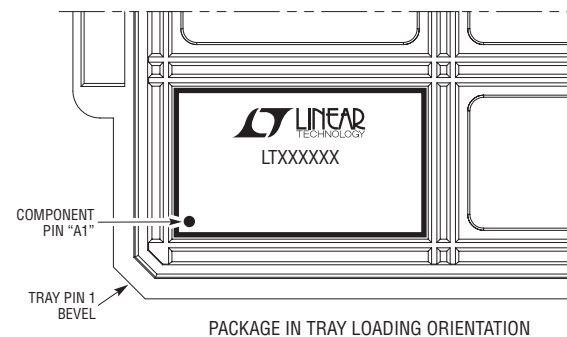
SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.39	1.54	1.69	
A1	0.35	0.40	0.45	
A2	1.04	1.14	1.24	
b	0.45	0.50	0.55	
b1	0.35	0.40	0.45	
D	15.00			
E	9.00			
e	0.80			
F	12.80			
G	7.20			
H1	0.39	0.44	0.49	
H2	0.65	0.70	0.75	
aaa			0.15	
bbb			0.10	
ccc			0.12	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 170

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
- ALL DIMENSIONS ARE IN MILLIMETERS
- BALL DESIGNATION PER JESD MS-028 AND JEP95
- DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
- PRIMARY DATUM -Z- IS SEATING PLANE
- SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC
- PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION